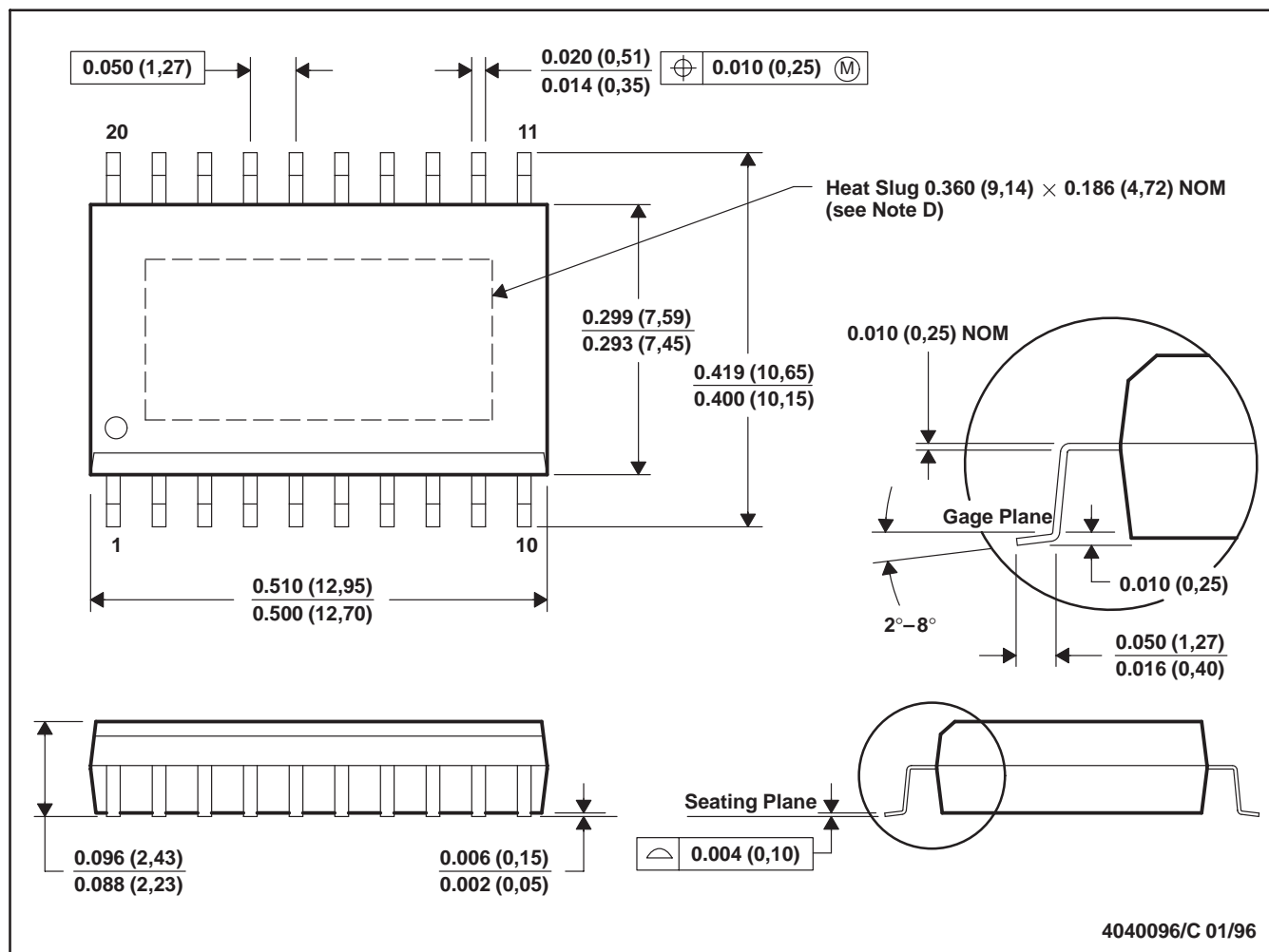


DWH (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Plastic body dimensions do not include mold protrusion. Maximum mold protrusion is 0.006 (0,15).
 D. Thermally enhanced molded plastic package with a heat slug (HSL) exposed on package bottom is electrically and thermally connected to the backside of the die and leads 3,4,7,8,12,13,16 and 17.

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